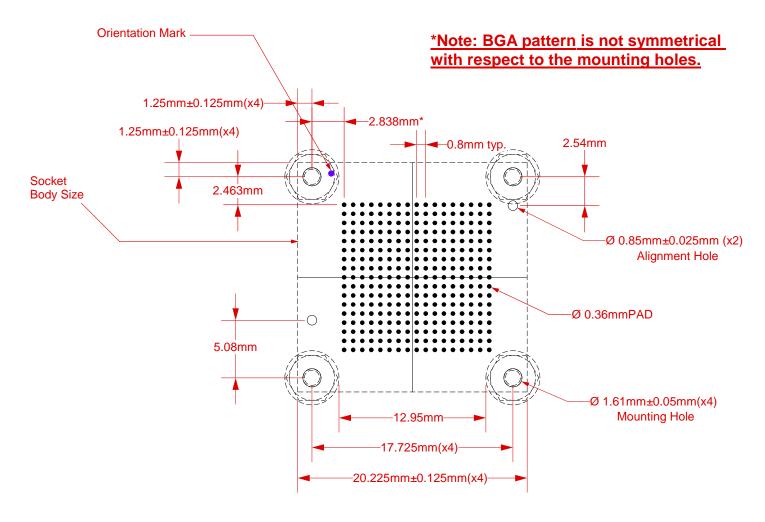


SG-BGA-6004 Drawing		Status: Released	Scale:	-	Rev: F
© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Meghann Fedde		Date: 8/16/01		
	File: SG-BGA-6004 Dwg.mcd		Modified: 07/02/09, AE		

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.



Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish

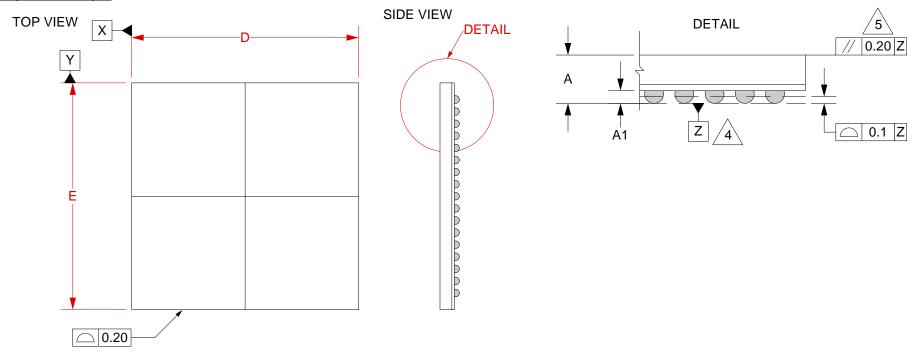
PCB Pad height: Same or higher than solder mask

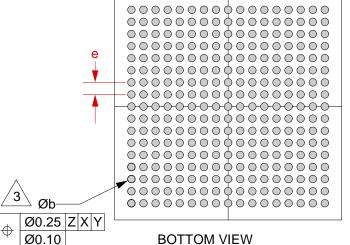
NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SG-BGA-6004 Drawing		Status: Released	Scale	: 3:1	Rev: F
© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Meghann Fedde		Date: 8/16/01		
	File: SG-BGA-6004 Dwg.mcd		Modified: 7/02/09, AE		







Dimensions are in millimeters.

Interpret dimensions and tolerances per ASME Y14.5M-1994.

Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.

Datum Z (seating plane) is defined by the spherical crowns of the solder balls.

Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX	
Α		2.5	
A1	0.2	0.34	
b		0.45	
D	15.0	0 BSC	
Е	15.00 BSC		
е	0.80 BSC		

Array 17x17

SG-BGA-6004 Drawing	Status: Released	Scale:	-	Rev: F
© 2009 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Meghann Fedde		Date: 8/16/01	
	File: SG-BGA-6004 Dwg.mcd		Modified: 7/02/09, AE	